



COPY OF PAPERS
ORIGINALLY FILED

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

Receipt 28

#3
FILE COPY Bell
62802

PATENT APPLICATION

Applicants: **Nallan et al.**

Case no.: **7017/ETCH/CONE**

Serial No.: **10/092,795** Filed: **March 6, 2002**

Group Art Unit: **2812**

Examiner: **Not yet assigned**

Title: **METHOD OF PLASMA ETCHING OF HIGH-K DIELECTRIC MATERIALS WITH HIGH SELECTIVITY TO UNDERLYING LAYERS**

ASSISTANT COMMISSIONER FOR PATENTS
Office of Initial Patent Examination's
Customer Service Center
Washington, D. C. 20231

S I R:

REQUEST FOR CORRECTED FILING RECEIPT

Applicants enclose herewith a copy of the Filing Receipt received in the above-captioned application and request a corrected Filing Receipt be issued to include the information indicated in red ink. Specifically, please change the attorney docket number to: 7017/ETCH/CONE.

Respectfully submitted,

Raymond R. Moser Jr.
Reg. No. 34,682
(732) 530-9404

5-21-02
Moser, Patterson & Sheridan, LLP
Attorneys at Law
595 Shrewsbury Avenue, Suite 100
Shrewsbury, NJ 07702

Please continue send all correspondence to:
Patent Counsel
Applied Materials, Inc.
P.O. Box 450A
Santa Clara, CA 95052

CERTIFICATE OF MAILING under 37 C.F.R. 1.8(a)

I hereby certify that this correspondence is being deposited on May 29, 2002 with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Kathleen Jirau
Signature 5-29-02
Date of signature



UNITED STATES PATENT AND TRADEMARK OFFICE

COPY OF PAPERS
ORIGINALLY FILED

Page 1 of 2

IDS 6-6-02

COPY DUE

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231
www.uspto.gov

APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY.DOCKET.NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/092,795	03/06/2002	2812	1076	7017/ETCH/GORE	4	34	4

CCNE

CONFIRMATION NO. 3410

FILING RECEIPT



OC000000007832499

Patent Counsel
Applied Materials, Inc.
3050 Bowers Avenue
P.O. Box 450A
Santa Clara, CA 95052

RECD APR 16 2002

Date Mailed: 04/09/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Padmapani C. Nallan, San Jose, CA;
Guangxiang Jin, San Jose, CA;
Ajay Kumar, Sunnyvale, CA;

Assignment For Published Patent Application

Applied Materials, Inc.;

Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 04/09/2002

Projected Publication Date: 09/11/2003

Non-Publication Request: No

Early Publication Request: No

Title

Method of plasma etching of high-K dielectric materials with high selectivity to underlying layers